IXYS

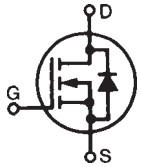
GigaMOS™ Power MOSFET

IXFR230N20T

V_{DSS}	=	200V
I_{D25}	=	156A
$R_{DS(on)}$	≤	8.0mΩ
t_{rr}	≤	200ns

(Electrically Isolated Tab)

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



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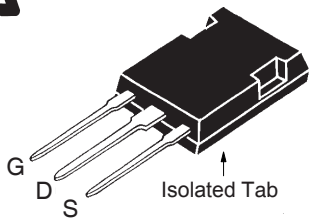

G = Gate D = Drain
S = Source

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	200	V
V_{DGR}	T_J = 25°C to 175°C, R_{GS} = 1MΩ	200	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	T_C = 25°C	156	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	630	A
I_A	T_C = 25°C	100	A
E_{AS}	T_C = 25°C	5	J
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le$ 175°C	20	V/ns
P_D	T_C = 25°C	600	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6mm (0.062 in.) from Case for 10s	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
V_{ISOL}	50/60 Hz, 1 Minute	2500	V~
F_C	Mounting Force	20..120/4.5..27	N/lb.
Weight		5	g

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 3mA	200			V
$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 8mA	3.0		5.0	V
I_{GSS}	V_{GS} = ± 20V, V_{DS} = 0V			± 200	nA
I_{DSS}	V_{DS} = V_{DSS}, V_{GS} = 0V			50	μA
	T_J = 150°C			3	mA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 60A, Note 1			8.0	mΩ

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 2500V~ Electrical Isolation
- Fast Intrinsic Diode
- Avalanche Rated
- Low Package Inductance

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- Synchronous Recification
- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC Motor Drives
- Uninterruptible Power Supplies
- High Speed Power Switching Applications

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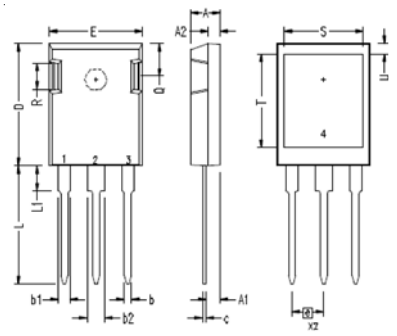
Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 60A, Note 1	90	150		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		24		nF
C_{oss}			2440		pF
C_{rss}			60		pF
R_{Gi}	Gate Input Resistance		1.15		Ω
$t_{d(on)}$	**Resistive Switching Times** V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = I_D = 0.5 • I_{D25} R_G = 1Ω (External)		58		ns
t_r			38		ns
$t_{d(off)}$			62		ns
t_f			17		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		358		nC
Q_{gs}			138		nC
Q_{gd}			60		nC
R_{thJC}				0.25	°C/W
R_{thCS}			0.15		°C/W

ISOPLUS247 (IXFR) Outline



1 = Gate
2,4 = Drain
3 = Source

SYM	INCHES MIN	MAX	MILLIMETERS MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b1	.075	.085	1.91	2.15
b2	.115	.126	2.92	3.20
C	.024	.033	0.61	0.83
D	.819	.840	20.80	21.34
E	.620	.635	15.75	16.13
e	.215 BSC		5.45 BSC	
L	.780	.811	19.81	20.60
L1	.150	.172	3.81	4.38
Q	.220	.244	5.59	6.20
R	.170	.191	4.32	4.85
S	.520	.540	13.21	13.72
T	.620	.640	15.75	16.26
U	.065	.080	1.65	2.03
W	0	.004	0	0.10

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			230	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			920	A
V_{SD}	I_F = 60A, V_{GS} = 0V, Note 1			1.3	V
t_{rr}	I_F = 115A, V_{GS} = 0V -di/dt = 100A/µs V_R = 75V			200	ns
Q_{RM}			0.74		µC
I_{RM}			10.6		A

Note 1: Pulse test, t ≤ 300µs, duty cycle, d ≤ 2%.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

Fig. 1. Output Characteristics @ T_J = 25ºC

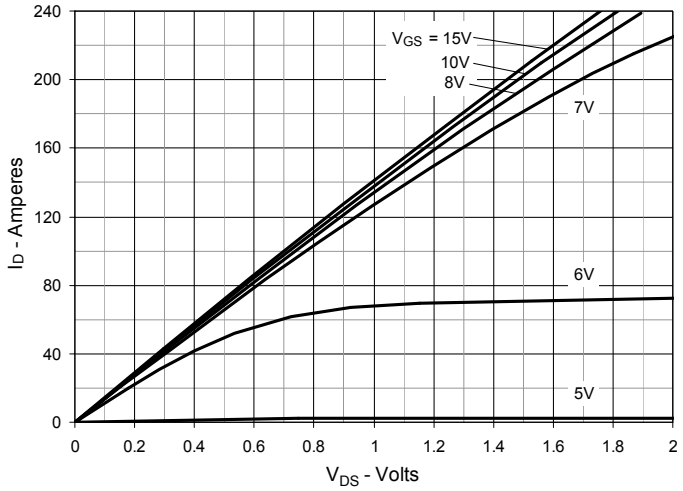


Fig. 2. Extended Output Characteristis @ T_J = 25ºC

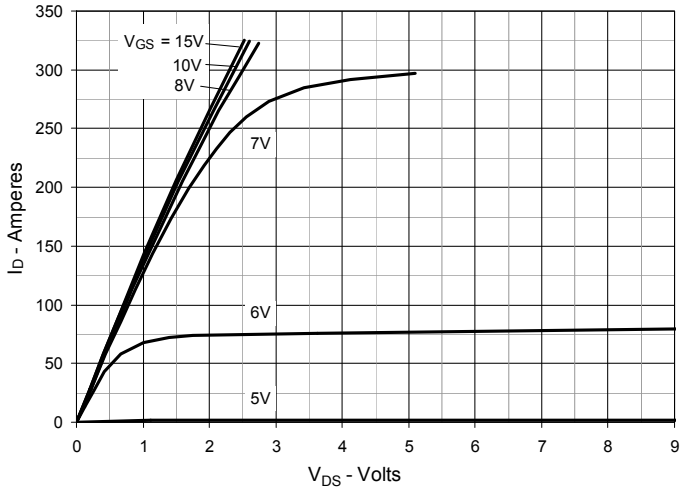


Fig. 3. Output Characteristics @ T_J = 150ºC

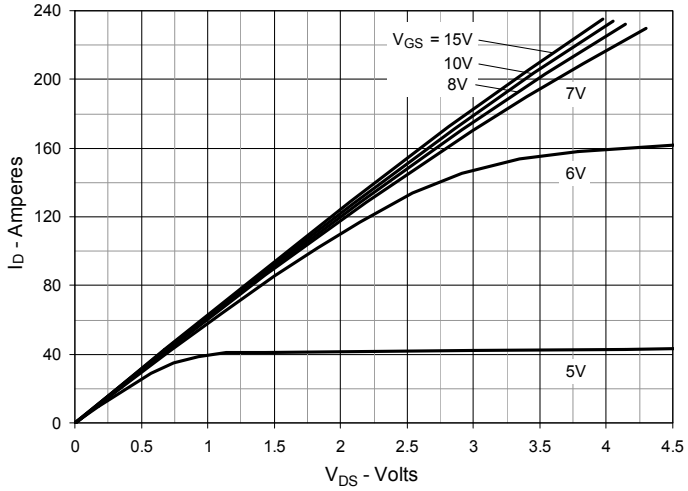


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 115A Value vs. Junction Temperature

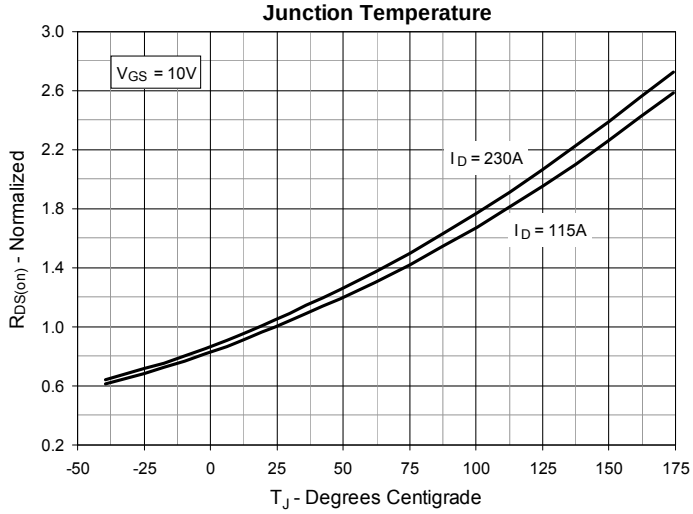


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 115A Value vs. Drain Current

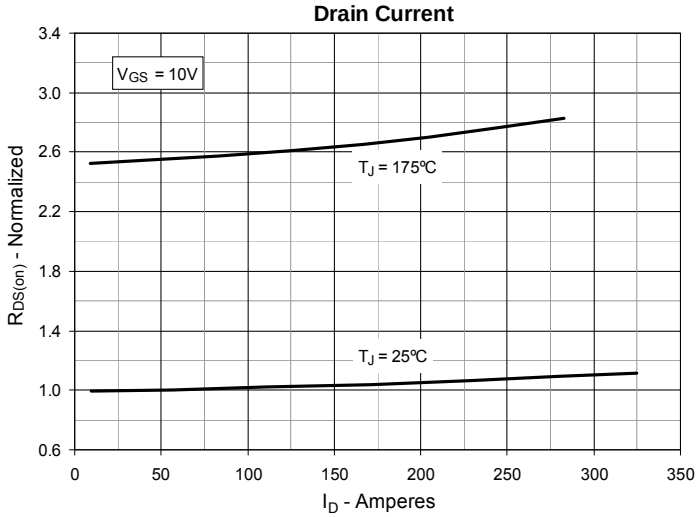


Fig. 6. Drain Current vs. Case Temperature

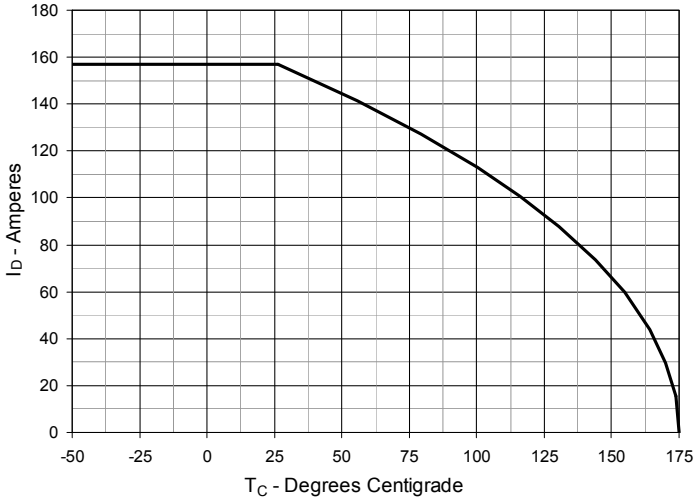


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Fig. 7. Input Admittance

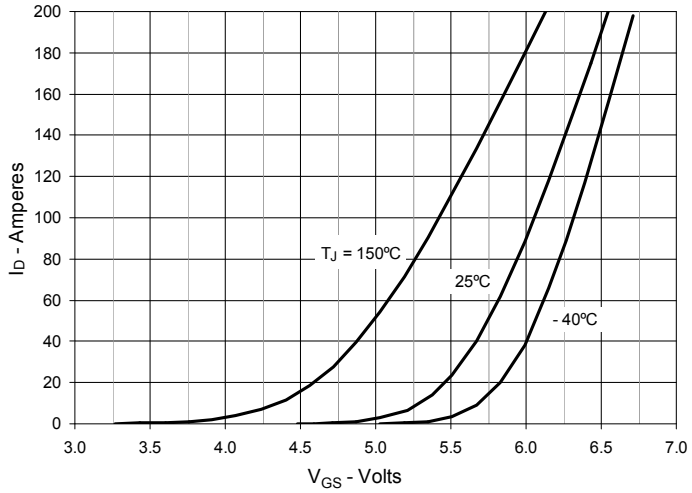

Fig. 8. Transconductance

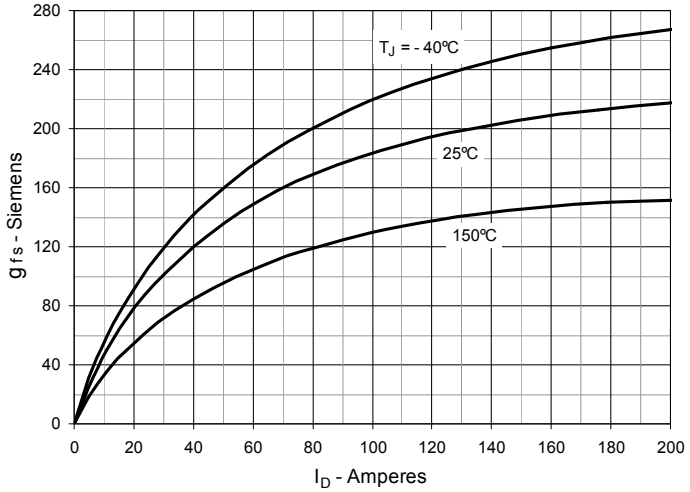

Fig. 9. Forward Voltage Drop of Intrinsic Diode

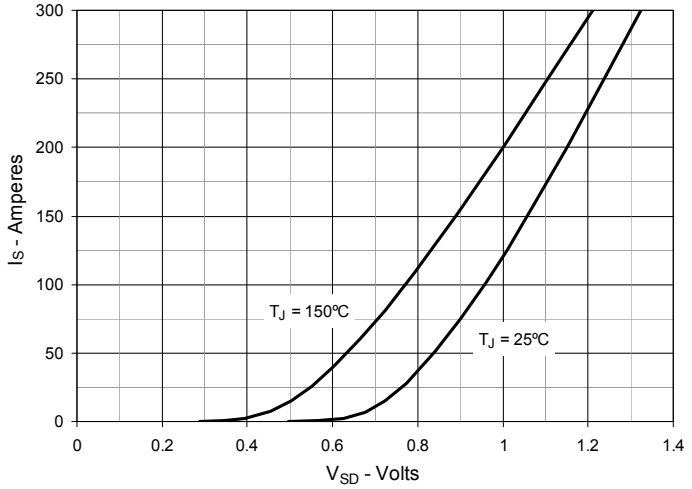

Fig. 10. Gate Charge

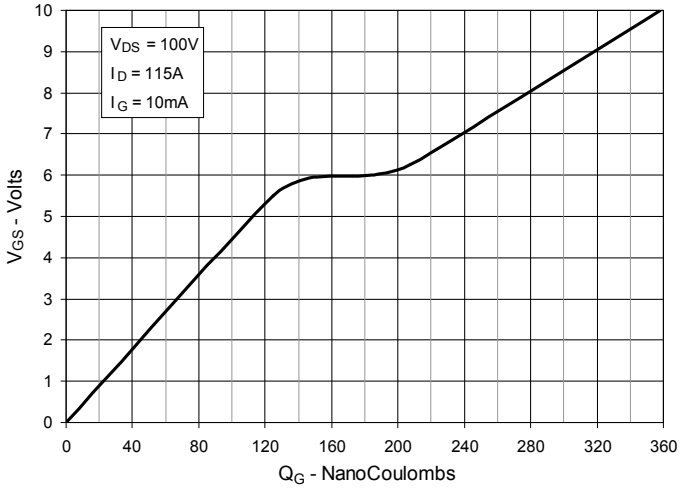

Fig. 11. Capacitance

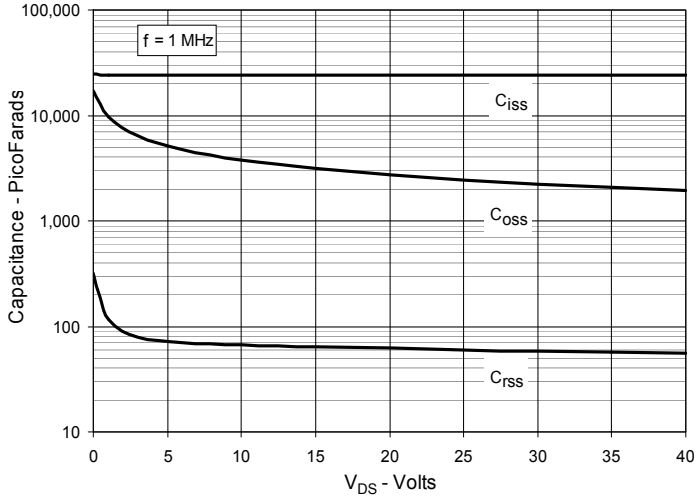

Fig. 12. Forward-Bias Safe Operating Area

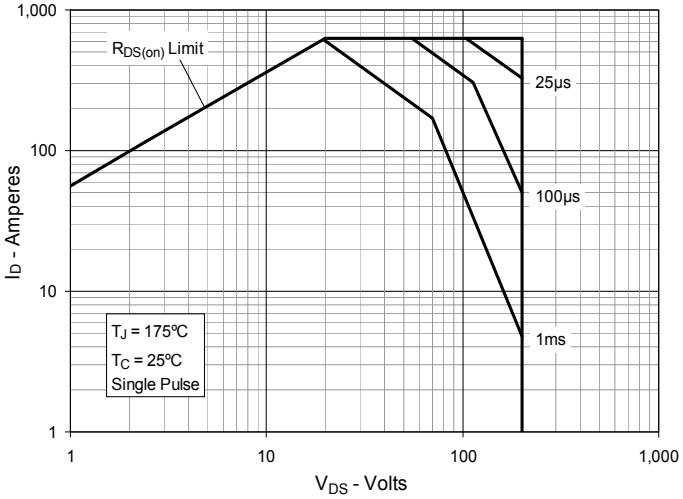

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Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

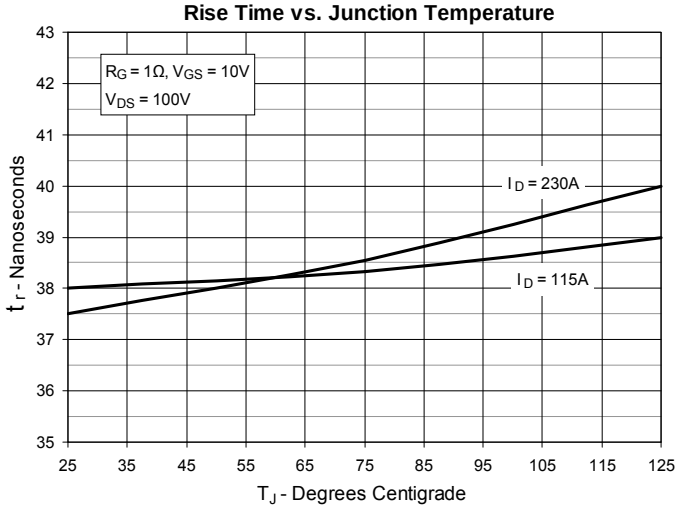

Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

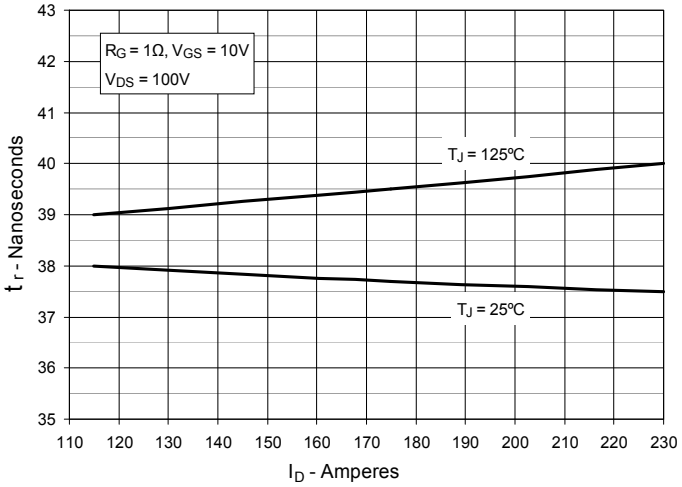

Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

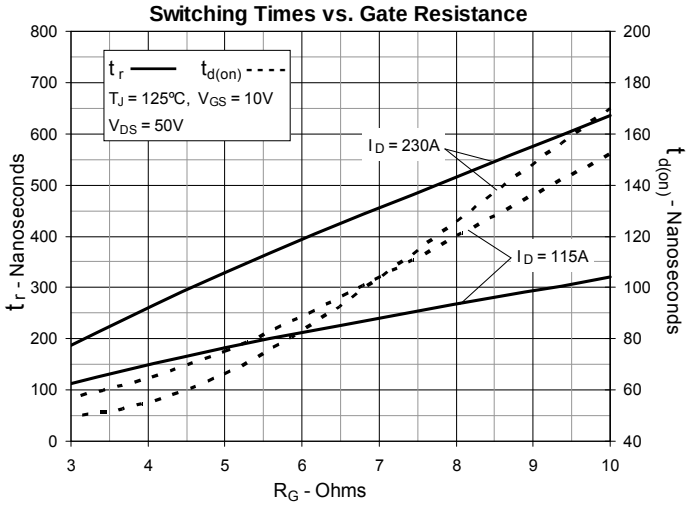

Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

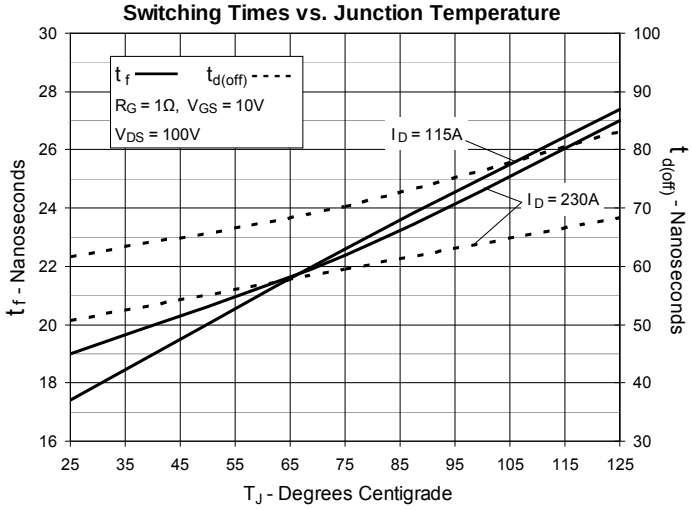

Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

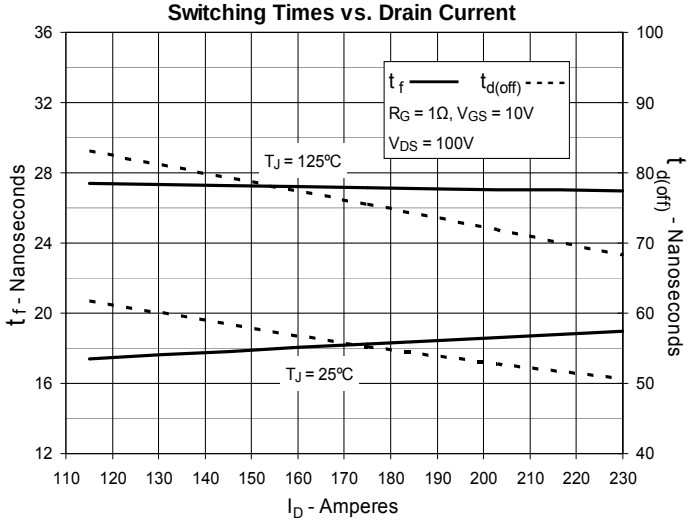

Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance

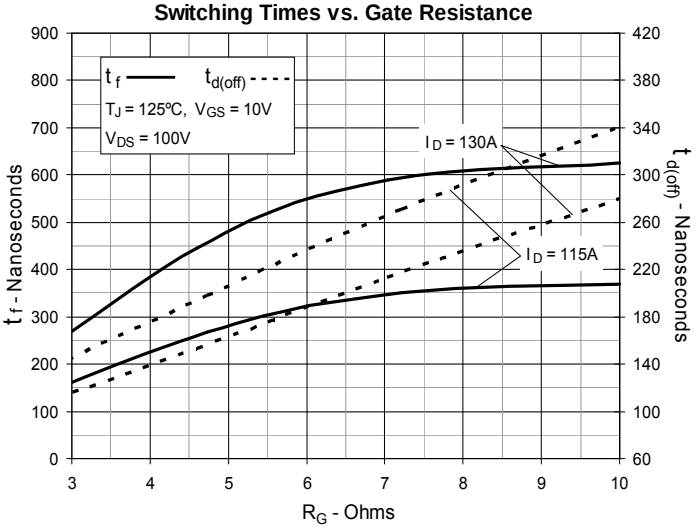

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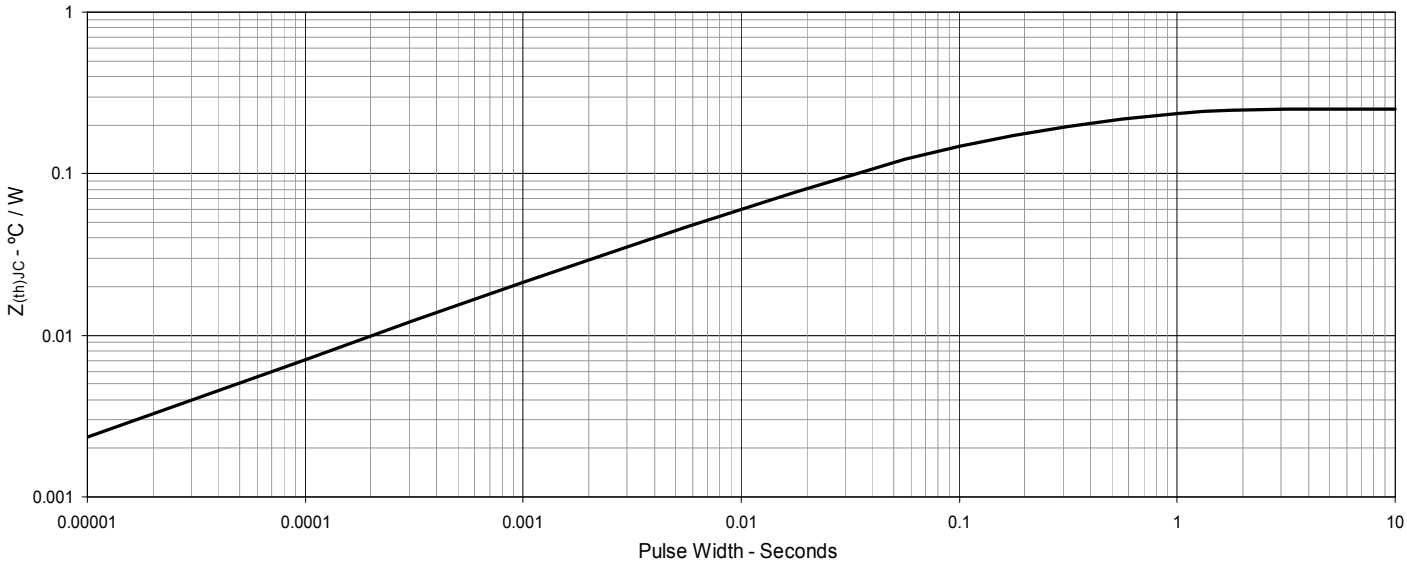
Fig. 19. Maximum Transient Thermal Impedance



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